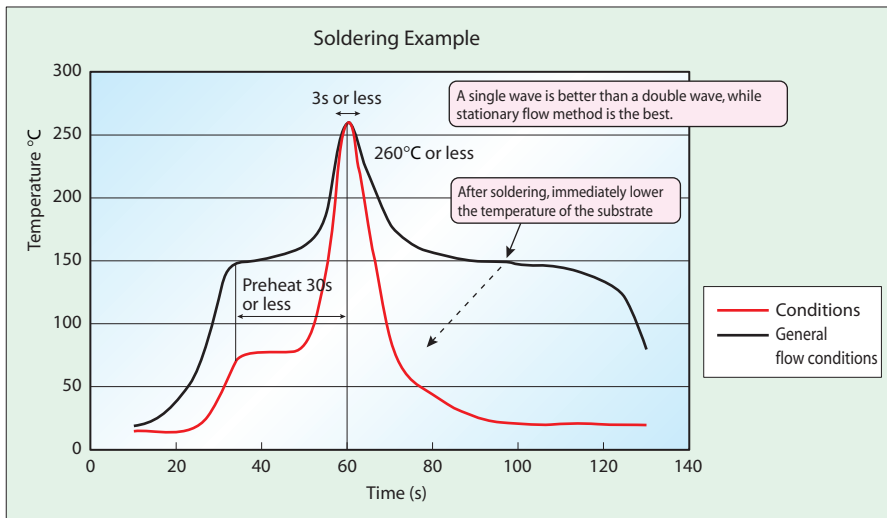


Solder Profile and Pattern

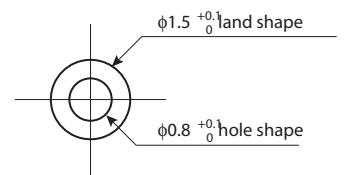
1) Dip Types (LA, LB ,LAP,LBP series)

Please keep the preheat and peak temperatures with dip units as low as possible and the times as short as possible, since the products are susceptible to heat during flow soldering. As a guide, ensure that the internal temperature of the LED numeric display does not exceed 100°C.

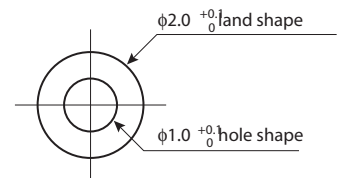


Solder Pattern Example

LA-301 series



Other series

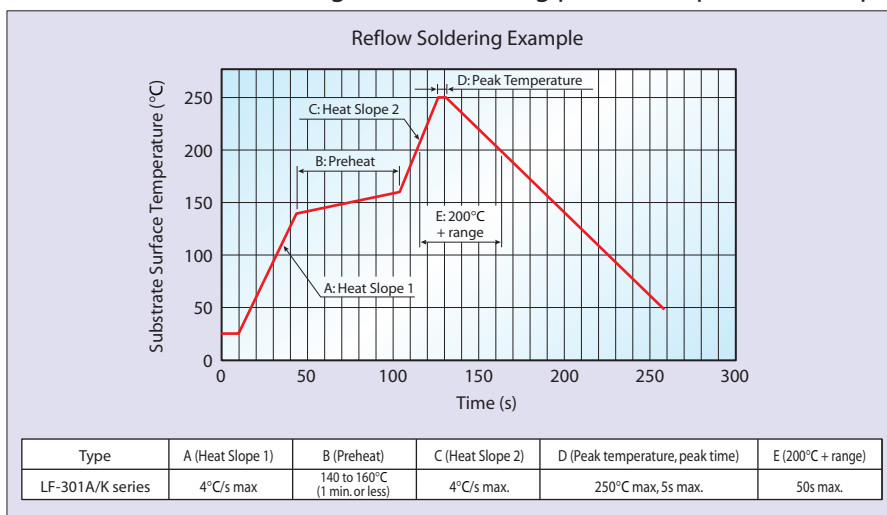


Item	Conditions	Solder Temperature	Process Duration
Solder dip	At least 2mm from the base of the lead pin.	Preheat temperature must be no greater than 80°C.	30 seconds or less
		No more than 260°C.	3 seconds or less
Solder iron	At least 2mm from the base of the lead pin. Power: No more than 30W.	No more than 300°C.	3 seconds or less
Reflow	Reflow cannot be used. (other than the LF-301 series)		

*Please use a resin-based flux, since flux that is acidic or highly alkaline could cause corrosion.

2) Surface Mount Type (LF-301 series)

Please refer to the following reflow soldering profile and pattern examples for surface mount units.



Solder Pattern Example

LF-301 A/K series

